

L Number	Hits	Search Text	DB	Time stamp
-	695380	substrate or wafer	USPAT; US-PGPUB	2004/07/26 12:33
-	1103373	ground\$4 or grind\$4 or cmp or polish\$4 or planar\$	USPAT; US-PGPUB	2004/07/26 12:34
-	1902876	back or backside or rear or rearside	USPAT; US-PGPUB	2004/07/26 12:34
-	9354	(substrate or wafer) with (ground\$4 or grind\$4 or cmp or polish\$4 or planar\$) with (back or backside or rear or rearside)	USPAT; US-PGPUB	2004/07/26 12:37
-	150814	seed\$4	USPAT; US-PGPUB	2004/07/26 12:38
-	700	((substrate or wafer) with (ground\$4 or grind\$4 or cmp or polish\$4 or planar\$) with (back or backside or rear or rearside)) and seed\$4	USPAT; US-PGPUB	2004/07/26 12:38
-	384472	bump or ball	USPAT; US-PGPUB	2004/07/26 12:38
-	212	((substrate or wafer) with (ground\$4 or grind\$4 or cmp or polish\$4 or planar\$) with (back or backside or rear or rearside)) and seed\$4) and (bump or ball)	USPAT; US-PGPUB	2004/07/26 13:37
-	488	((substrate or wafer) with (ground\$4 or grind\$4 or cmp or polish\$4 or planar\$) with (back or backside or rear or rearside)) and seed\$4) not (((substrate or wafer) with (ground\$4 or grind\$4 or cmp or polish\$4 or planar\$) with (back or backside or rear or rearside)) and seed\$4) and (bump or ball))	USPAT; US-PGPUB	2004/07/26 13:44